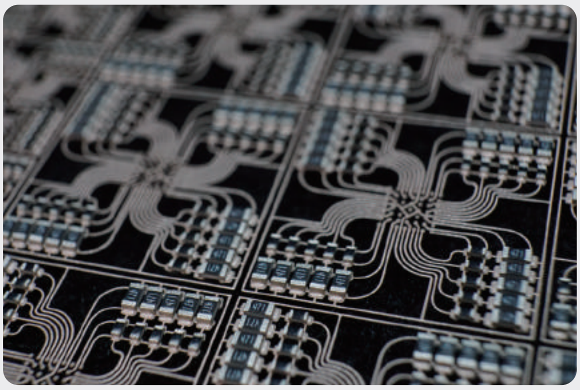
# Low Temperature Curable SMT Paste

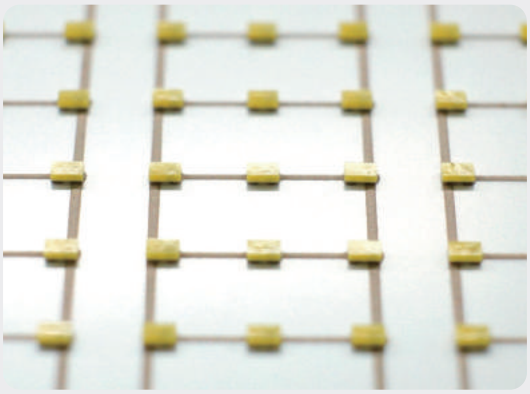
Suitable to low heat resistance substrates

## Applications

### Chip mounting



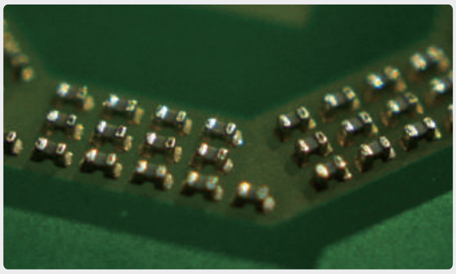
e.g. : Glass wafers



e.g. : LED chip mounting on polyimide substrates

## Features

- Low temperature process
- Excellent adhesion
- Excellent stress absorption



0201 chip mounting

## Product line-up & properties

| Product | | | AE8010 |
|---|---|---|---|
| Filler | Conductive particles | | Silver coated copper |
| | Average particle size | μm | 4 - 6 |
| Binder | Resin | | Epoxy |
| Filling ratio | | wt% | 84 - 88 |
| Viscosity | BH type | dPa·s | 1,000 - 1,500 |
| Density | | g/cm$^3$ | 4.4 |
| Curing conditions | Curing | | 120℃×30min. |
| Volume resistivity (Representative value) | | Ω·cm | 1.5E-04 |
| Thermal conductivity | | W/m·k | 10 |
| Shelf-life | -15 - -40℃ | month(s) | 2.0 |

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